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AN 107:11597 HCA
TI **Copper**-based alloys for semiconductor lead frames
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PA Mitsubishi Electric Corp., Japan
SO Jpn. Kokai Tokkyo Koho, 3 pp.
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AB The alloys contain **Fe** 0.5-3, **Ni** 0.4-2, **P** 0.01-0.5, and **Sn** 0.15-1.5%. The alloys contain uniformly dispersed **Ni-P**, **Fe-P**, and **Ni-Sn** compds., show good elec. cond. and high strength, and can be manufd. at a low cost. A **Cu** alloy ingot contg. **Fe** 0.70, **Ni** 0.62, **P** 0.06, and **Sn** 0.21%, prepd. by melting and casting in air was hot rolled, surface ground, and repeatedly cold rolled and process annealed with finishing draft 37% to give a sheet 0.25 mm thick. The sheet showed Vickers hardness 154 and elec. cond. 48% IACS, vs. 172, and 50% IACS for a similarly prepd. sheet of conventional C19500.